

HZL6.2Z4

Silicon Planar Zener Diode for Surge Absorb

REJ03G0409-0100 Rev.1.00 Oct 01, 2004

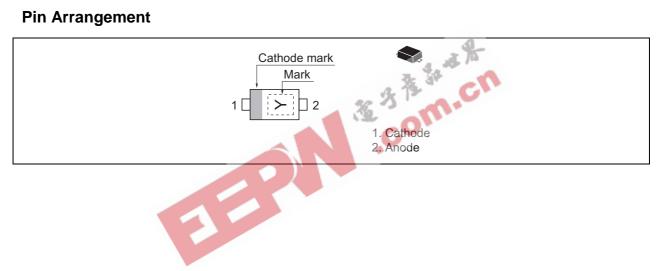
## **Features**

- Low capacitance (C = 4.0 pF max) and can protect ESD of signal line.
- Extremely small Flat Package (EFP) is suitable for surface mount design.

## **Ordering Information**

Type No.	Laser Mark	Package Code
HZL6.2Z4	Y	EFP

## **Pin Arrangement**





# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Power dissipation	Pd *	100	mW
Junction temperature	Тј	150	°C
Storage temperature Tstg		-55 to +150	°C

Note: See Fig.2.

## **Electrical Characteristics**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Zener voltage	Vz	5.90	-	6.50	V	$I_Z = 5 \text{ mA}, 40 \text{ ms pulse}$
Reverse current	I <sub>R</sub>	-	-	3	μA	V <sub>R</sub> = 5.5 V
Capacitance	С	-	-	4.0	pF	$V_R = 0 V, f = 1 MHz$
Dynamic resistance	r <sub>d</sub>	-	-	60	Ω	$I_Z = 5 \text{ mA}$
ESD-Capability *1	—	8	_	—	kV	C = 150 pF, R = 330 $\Omega$ , Both Forward and reverse direction 10 pulse

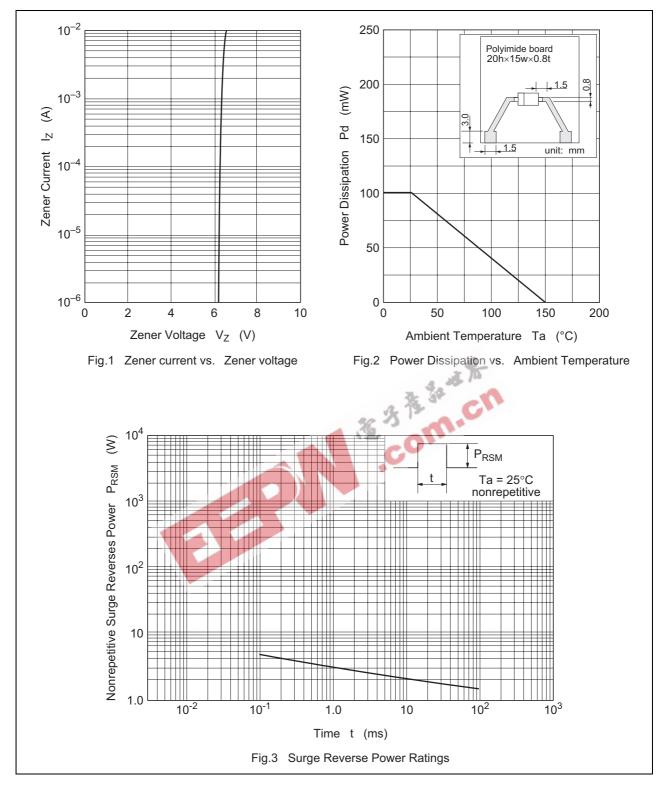
Notes: 1. Failure criterion ;  $I_R > 3 \ \mu A$  at  $V_R = 5.5 \ V$ .

2. Please do not use the soldering iron due to avoid high stress to the EFP package.

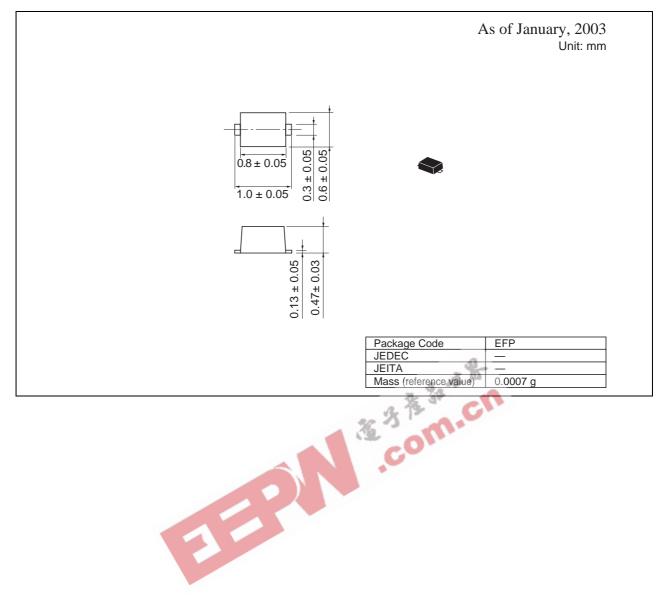
بacki ung nature C. ung nature. 3. The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.



# **Main Characteristic**



## **Package Dimensions**





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